PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
KUAN-YU LIN	01/14/2016
CHIN-HER CHIEN	01/14/2016
JI-JAN CHEN	01/14/2016
JUNG-RUNG JIANG	01/14/2016
WEI-PIN CHANGCHIEN	01/14/2016

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15043912

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NAME OF SUBMITTER:	DAVID M. O'DELL
SIGNATURE:	/David O'Dell/
DATE SIGNED:	07/13/2016

Total Attachments: 3
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source=Inventors_Assignment#page3.tif

Docket No.: P20130839US01/24061.2619US02
Customer No.: 000042717

ASSIGNMENT

WHEREAS, we,

(1)	Kuan-Yu Lin	of	Hsinchu County 310, Taiwan (R.O.C.)
(2)	Chin-Her Chien	of	Taoyuan County, Taiwan 300-77 (R.O.C.)
(3)	Ji-Jan Chen	of	Kaohsiung City 806,Taiwan (R.O.C.)
(4)	Jung-Rung Jiang	of	Chung-Li City, Taiwan 300-77, (R.O.C.)
(5)	Wei-Pin Changchien	of	Taichung City, Taiwan 300-77, (R.O.C.)

have invented certain improvements in

REPAIRING MONOLITHIC STACKED INTEGRATED CIRCUITS WITH A REDUNDANT LAYER AND LITHOGRAPHY PROCESS

for which we have executed an application for Letters Patent of the United States of America,

   __X__   of even date filed herewith; and

   _____   filed on 02-15-2016 and assigned application number 15/043,912, and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Kuan-Yu Lin

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                      Hsinchu County 310, Taiwan (R.O.C.)

Dated: _Jan, 14, 2016_   _Kuan-Yu Lin._
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                                Inventor Signature

Inventor Name: Chin-Her Chien

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Dated: _Jan, 14, 2011_   _Chin-Her chien_
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                                Inventor Signature

Inventor Name: Ji-Jan Chen

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                      Kaohsiung City 806, Taiwan (R.O.C.)
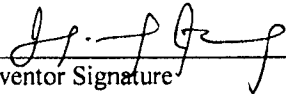
Dated: _Jan. 14th, 2016_   _Ji-Jan Ch_
                                _____
                                Inventor Signature

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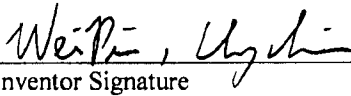Dated: _____Jan, 14, 2016_____   _____
                                        Inventor Signature

Inventor Name: Wei-Pin Changchien

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Dated: _____Jan. 14. 2016_____   _____
                                        Inventor Signature